SQ2361ES-T1_GE3-VB Datasheet
P-Channel 60-V (D-S) MOSFET

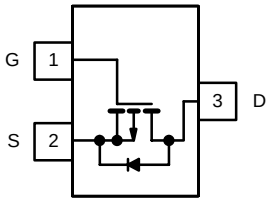
PRODUCT SUMMARY		
V_{DS} (V)	- 60	
$R_{DS(on)}$ (Ω)	V_{GS} = - 10 V	0.05
Q_g (Max.) (nC)	12	
Q_{gs} (nC)	3.8	
Q_{gd} (nC)	5.1	
Configuration	Single	

FEATURES

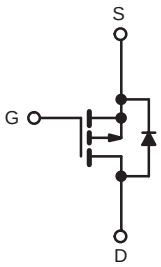
- Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz)
- Sink to Lead Creepage Distance = 4.8 mm
- P-Channel
- 175 °C Operating Temperature
- Dynamic dV/dt Rating
- Low Thermal Resistance
- Lead (Pb)-free Available

Available
RoHS* COMPLIANT

TO-236
(SOT-23)



Top View



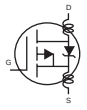
P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted					
PARAMETER			**SYMBOL**	**LIMIT**	**UNIT**
Drain-Source Voltage			V_{DS}	- 60	V
Gate-Source Voltage			V_{GS}	± 20	
Continuous Drain Current	V_{GS} at - 10 V	T_C = 25 °C	I_D	- 5.2	A
		T_C = 100 °C		- 3.8	
Pulsed Drain Current[a]			I_{DM}	- 21	
Linear Derating Factor				0.18	W/°C
Single Pulse Avalanche Energy[b]			E_{AS}	120	mJ
Repetitive Avalanche Current[a]			I_{AR}	- 5.2	A
Repetitive Avalanche Energy[a]			E_{AR}	2.7	mJ
Maximum Power Dissipation	T_C = 25 °C		P_D	27	W
Peak Diode Recovery dV/dt[c]			dV/dt	- 4.5	V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s			300[d]	
Mounting Torque	6-32 or M3 screw			10	lbf · in
				1.1	N · m

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. V_{DD} = - 25 V, starting T_J = 25 °C, L = 5.0 mH, R_G = 25 Ω, I_{AS} = - 5.3 A (see fig. 12).
c. $I_{SD} \leq$ - 6.7 A, dI/dt ≤ 90 A/µs, $V_{DD} \leq V_{DS}$, $T_J \leq$ 175 °C.
d. 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	5.5	

SPECIFICATIONS T_J = 25 °C, unless otherwise noted						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = - 250 µA	- 60	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = - 1 mA	-	- 0.060	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = - 250 µA	- 1.0	-	- 2.5	V
Gate-Source Leakage	I_{GSS}	V_{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V	-	-	- 100	µA
		V_{DS} = - 48 V_{GS} = 0 V, T_J = 150 °C	-	-	- 500	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = - 10 V, I_D = - 3.2 A[b]	-	0.05	-	Ω
Forward Transconductance	g_{fs}	V_{DS} = - 25 V, I_D = - 3.2 A[b]	1.6	-	-	S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = - 25 V, f = 1.0 MHz, see fig. 5	-	270	-	pF
Output Capacitance	C_{oss}		-	170	-	
Reverse Transfer Capacitance	C_{rss}		-	31	-	
Drain to Sink Capacitance	C	f = 1.0 MHz	-	12	-	
Total Gate Charge	Q_g	V_{GS} = - 10 V, I_D = - 4.7 A, V_{DS} = - 48 V, see fig. 6 and 13[b]	-	-	12	nC
Gate-Source Charge	Q_{gs}		-	-	3.8	
Gate-Drain Charge	Q_{gd}		-	-	5.1	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = - 30 V, I_D = - 4.7 A, R_G = 24 Ω, R_D= 4.0 Ω, see fig. 10[b]	-	11	-	ns
Rise Time	t_r		-	63	-	
Turn-Off Delay Time	$t_{d(off)}$		-	9.6	-	
Fall Time	t_f		-	31	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact 	-	4.5	-	nH
Internal Source Inductance	L_S		-	7.5	-	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	- 5.2	A
Pulsed Diode Forward Current[a]	I_{SM}		-	-	- 21	
Body Diode Voltage	V_{SD}	T_J = 25 °C, I_S = - 5.2 A, V_{GS} = 0 V[b]	-	-	- 5 .5	V
Body Diode Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = - 4.7 A, dI/dt = 100 A/µs[b]	-	80	160	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	0.096	0.19	µC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)				

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).

b. Pulse width ≤ 300 µs; duty cycle ≤ 2 %.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

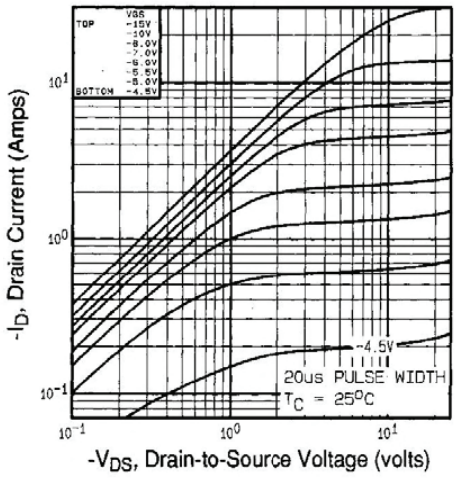


Fig. 1 - Typical Output Characteristics, T_C= 25 °C

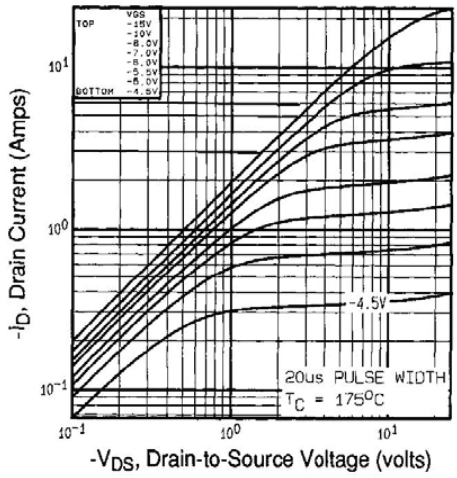


Fig. 2 - Typical Output Characteristics, T_C= 175 °C

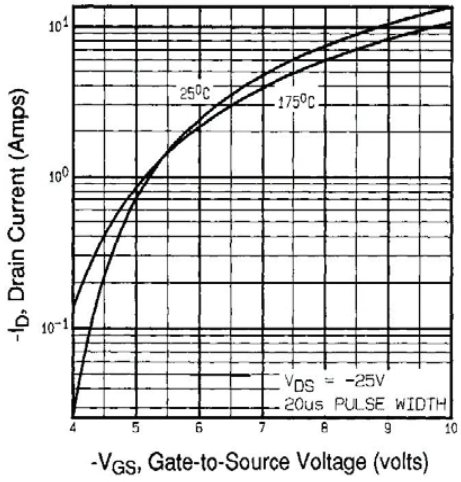


Fig. 3 - Typical Transfer Characteristics

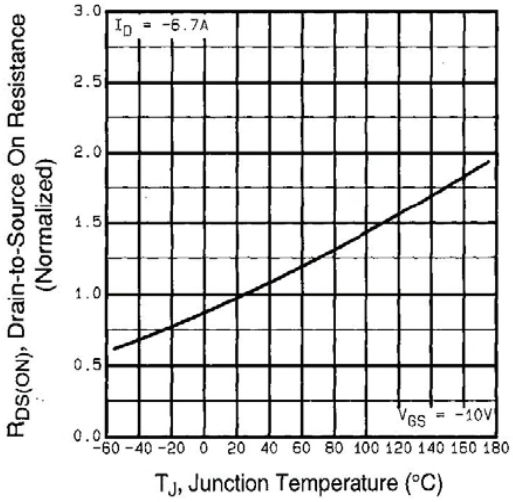


Fig. 4 - Normalized On-Resistance vs. Temperature

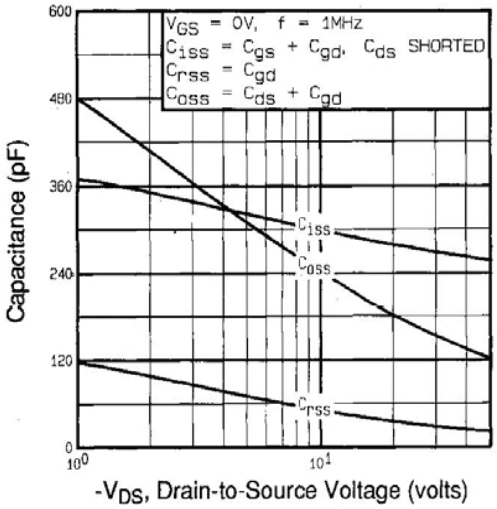


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

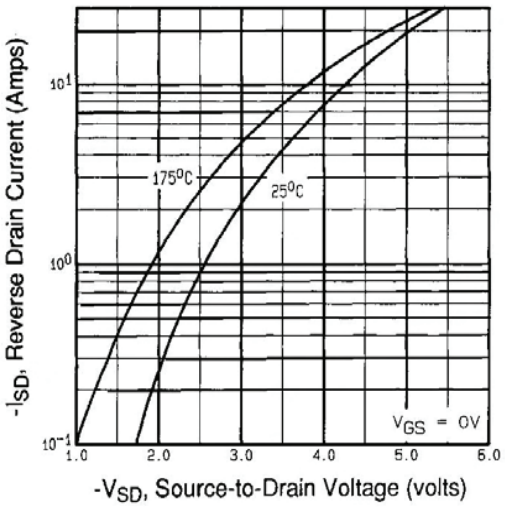


Fig. 7 - Typical Source-Drain Diode Forward Voltage

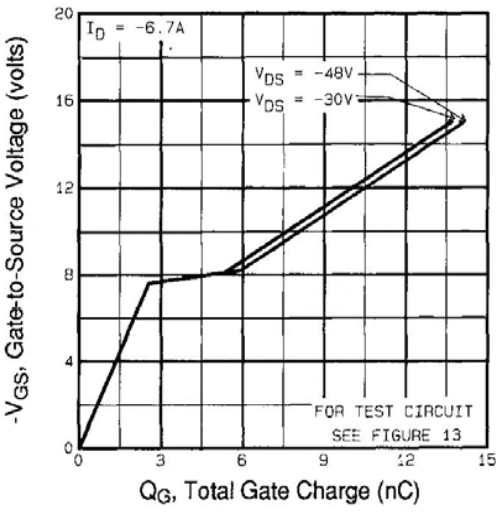


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

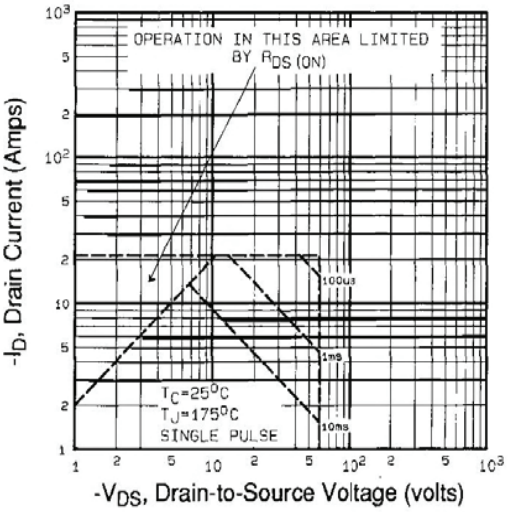


Fig. 8 - Maximum Safe Operating Area

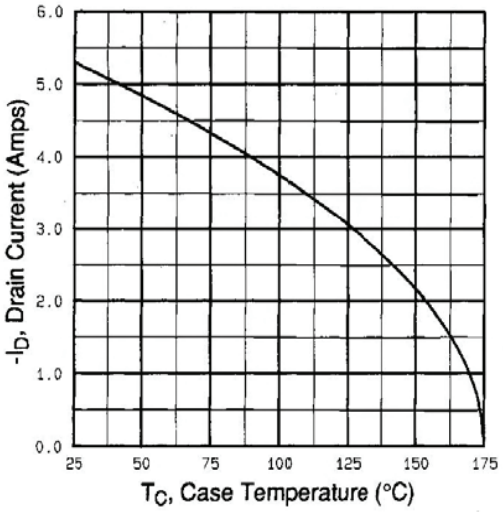


Fig. 9 - Maximum Drain Current vs. Case Temperature

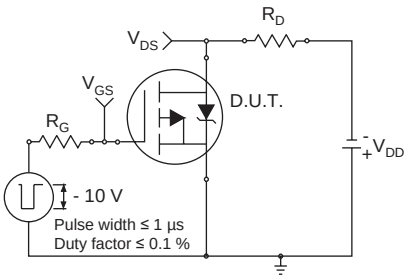


Fig. 10a - Switching Time Test Circuit

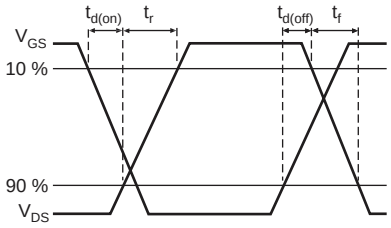


Fig. 10b - Switching Time Waveforms

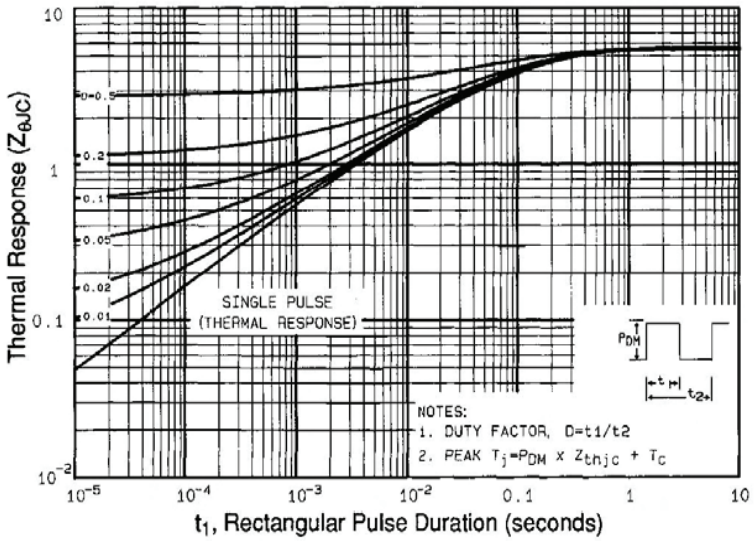


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

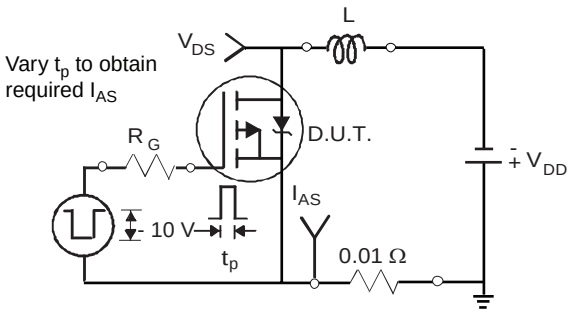


Fig. 12a - Unclamped Inductive Test Circuit

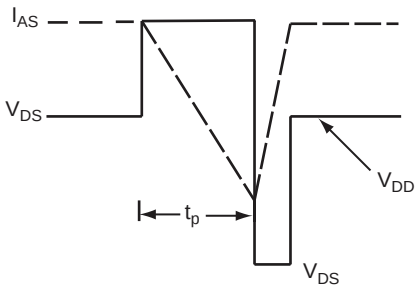


Fig. 12b - Unclamped Inductive Waveforms

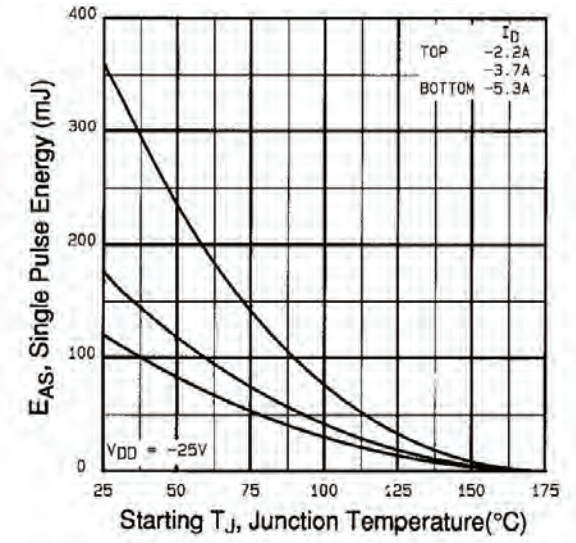


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

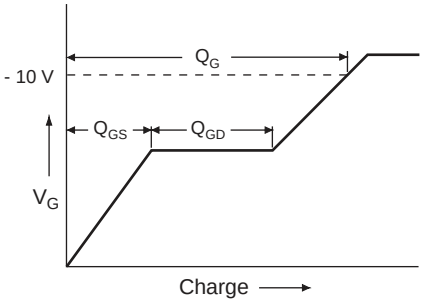


Fig. 13a - Basic Gate Charge Waveform

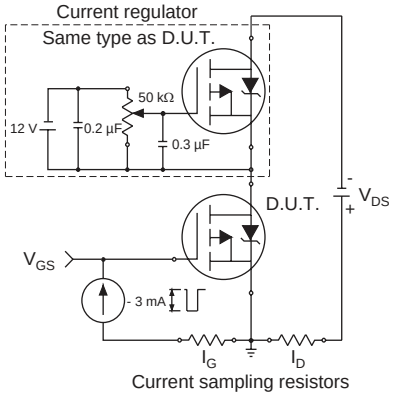
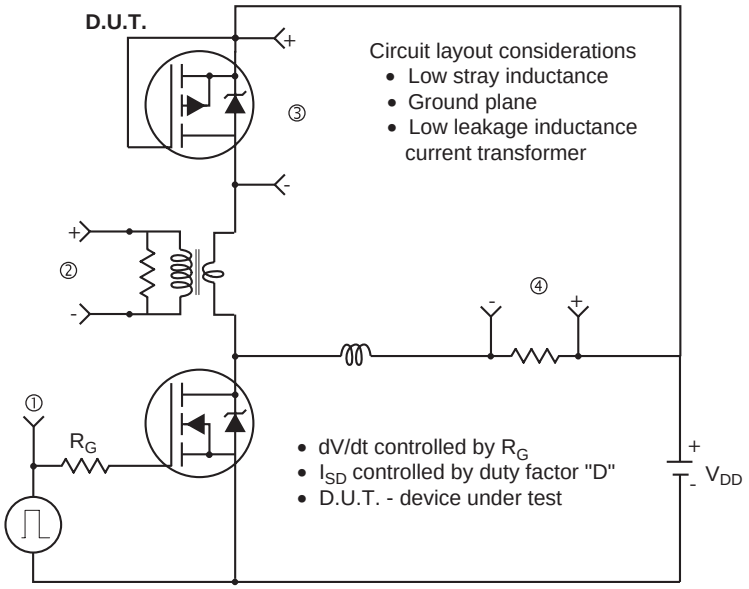
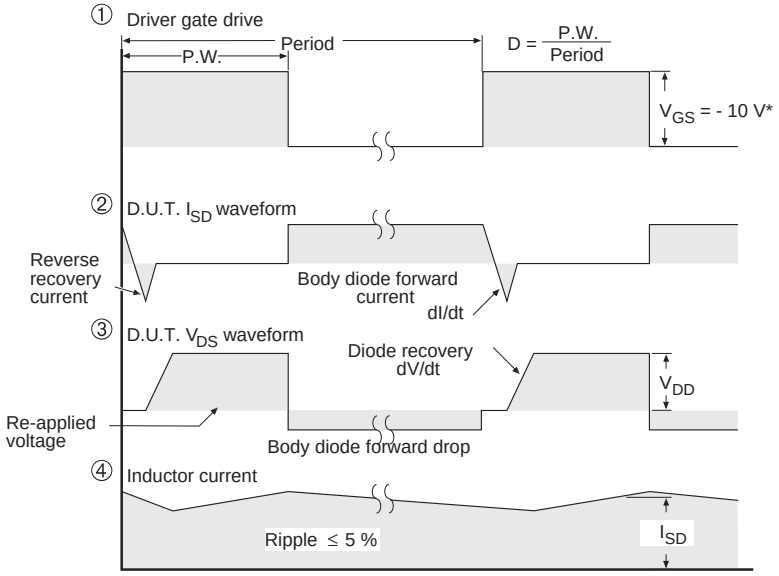


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



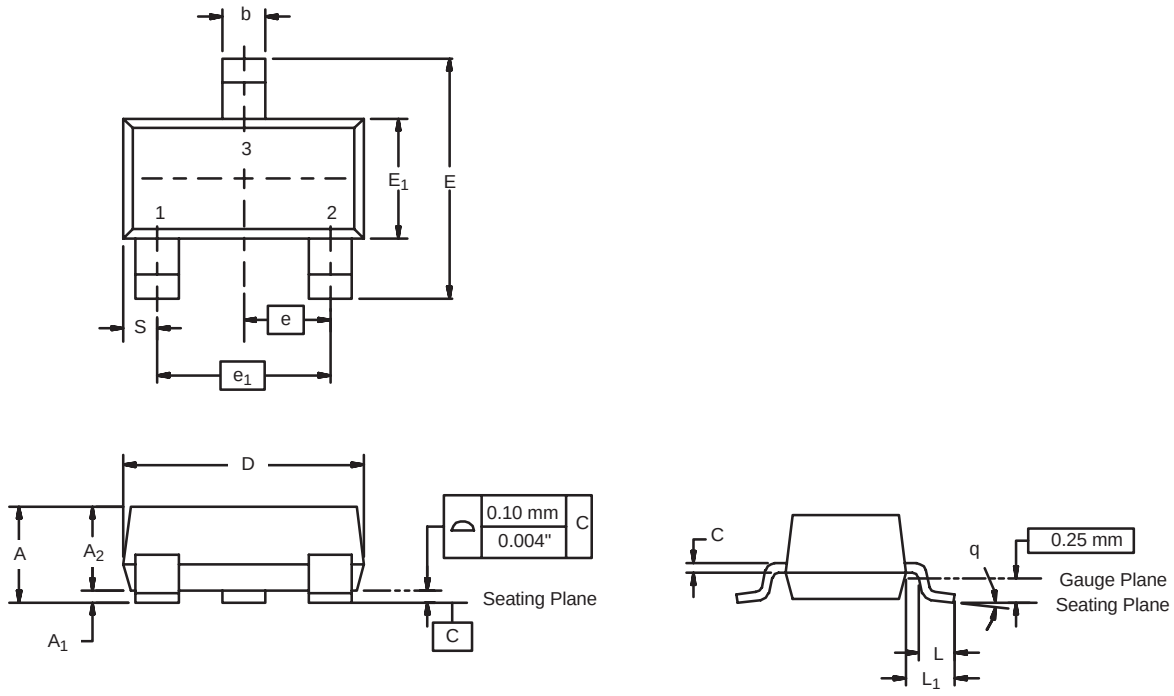
• Compliment N-Channel of D.U.T. for driver



* V_{GS} = - 5 V for logic level and - 3 V drive devices

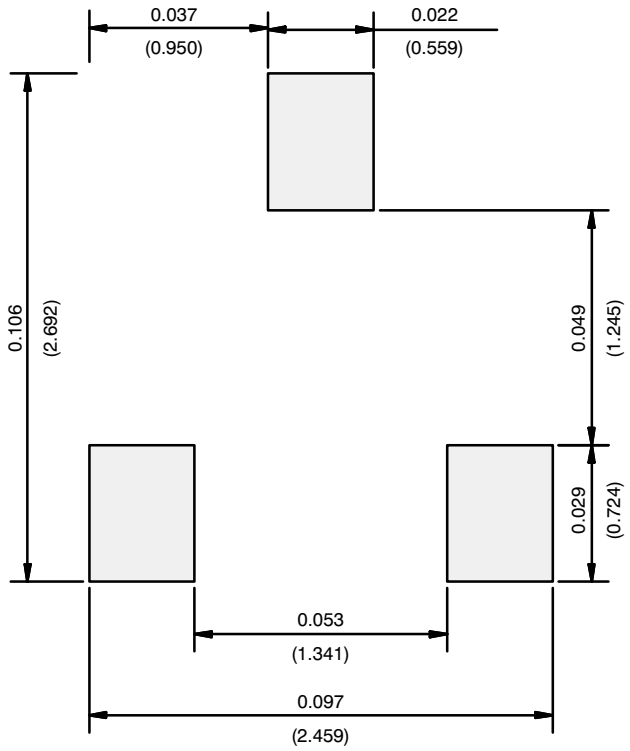
Fig. 14 - For P-Channel

SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A_1	0.01	0.10	0.0004	0.004
A_2	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E_1	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e_1	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L_1	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°
ECN: S-03946-Rev. K, 09-Jul-01 DWG: 5479				

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

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